



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

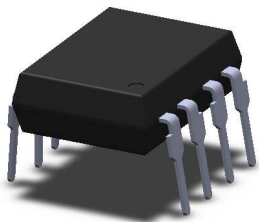
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



8 PIN DIP WIDE BODY HIGH SPEED 1Mbit/s TRANSISTOR PHOTOCOUPLER ELW135 ELW136 ELW4503



Features

- High speed 1Mbit/s
- High isolation voltage between input and output (Viso=5000 Vrms)
- Guaranteed performance from 0°C to 70 °C
- Wide operating temperature range of -55°C to 100 °C
- Pb free and RoHS compliant
- UL approved (No. 214129)
- VDE approved (No. 40028391)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved

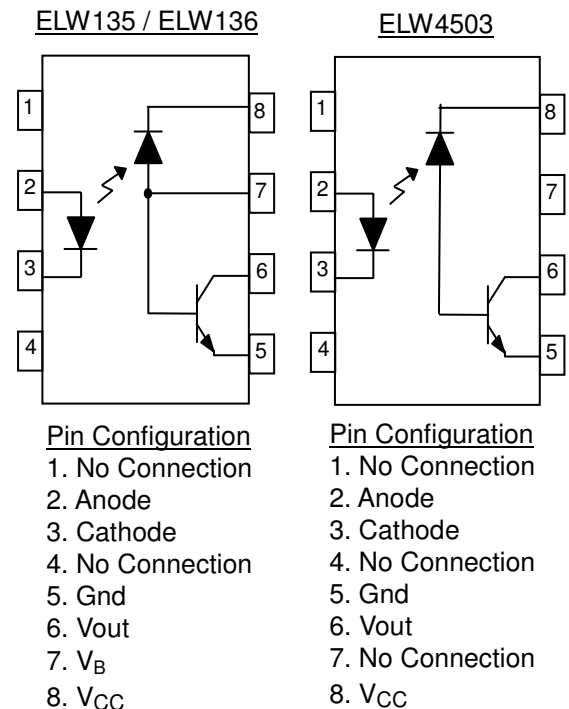
Description

The ELW135, ELW136 and ELW4503 devices each consist of an infrared emitting diode, optically coupled to a high speed photo detector transistor. A separate connection for the photodiode bias and output-transistor collector increase the speed by several orders of magnitude over conventional phototransistor couplers by reducing the base-collector capacitance of the input transistor. The devices are packaged in an 8-pin DIP wide body package and available in wide-lead spacing and SMD option.

Applications

- Line receivers
- Telecommunication equipments
- Power transistor isolation in motor drives
- Replacement for low speed phototransistor photo couplers
- Feedback loop in switch-mode power supplies
- Home appliances
- High speed logic ground isolation

Schematic



Absolute Maximum Ratings (Ta=25°C)

Parameter		Symbol	Rating	Unit
Input	Forward current	I_F	25	mA
	Peak forward current (50% duty, 1ms P.W)	I_{FP}	50	mA
	Peak transient current ($\leq 1\mu s$ P.W, 300pps)	I_{Ftrans}	1	A
	Reverse voltage	V_R	5	V
	Power dissipation	P_{IN}	45	mW
Power dissipation		P_O	100	mW
Output	Emitter-Base reverse voltage	ELW135 ELW136 V_{EBR}	5	V
	Base current	ELW135 ELW136 I_B	5	mA
	Average Output current	$I_{O(AVG)}$	8	mA
	Peak Output current	$I_{O(PK)}$	16	mA
	Output voltage	V_O	-0.5 to 20	V
	Supply voltage	V_{CC}	-0.5 to 30	V
Isolation voltage ^{*1}		V_{ISO}	5000	V rms
Operating temperature		T_{OPR}	-55 ~ +100	°C
Storage temperature		T_{STG}	-55 ~ +125	°C
Soldering temperature ^{*2}		T_{SOL}	260	°C

Notes:

*1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2, 3, 4 are shorted together, and pins 5, 6, 7, 8 are shorted together.

*2 For 10 seconds

Electrical Characteristics (T_A=0 to 70 °C unless specified otherwise)

Input

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward voltage	V _F	-	1.45	1.8	V	I _F = 16mA
Reverse Voltage	V _R	5.0	-	-	V	I _R = 10μA
Temperature coefficient of forward voltage	ΔV _F /ΔT _A	-	-1.9	-	mV/°C	I _F = 16mA

Output

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Logic High Output Current	I _{OH}	-	0.001	0.5	μA	I _F =0mA, V _O =V _{CC} =5.5V, T _A =25 °C
		-	0.01	1		I _F =0mA, V _O =V _{CC} =15V, T _A =25 °C
		-	-	50		I _F =0mA, V _O =V _{CC} =15V
Logic Low Supply Current	I _{CCL}	-	110	200	μA	I _F =16mA, V _O =Open, V _{CC} =15V
Logic High Supply Current	I _{CCH}	-	0.01	1	μA	I _F =0mA, V _O =Open, V _{CC} =15V, T _A =25 °C
		-	-	2		I _F =0mA, V _O =Open, V _{CC} =15V

* Typical values at T_A = 25 °C

Transfer Characteristics ($T_A=0$ to 70°C unless specified otherwise)

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition	
Current Transfer Ratio	ELW135	7	-	50	%	$I_F = 16\text{mA}, V_O = 0.4\text{V}, V_{CC}=4.5\text{V}, T_A=25^\circ\text{C}$	
	ELW 136	19	-	50			
	ELW4502						
	ELW4503						
	ELW135	5	-	-			$I_F = 16\text{mA}, V_O = 0.5\text{V}, V_{CC}=4.5\text{V}$
	ELW 136	15	-	-			
ELW4502 ELW4503							
Logic Low Output Voltage	ELW135	-	0.18	0.4	V	$I_F = 16\text{mA}, I_O = 1.1\text{mA}, V_{CC}=4.5\text{V}, T_A=25^\circ\text{C}$	
	ELW 136	-	0.25	0.4			
	ELW4502 ELW4503						
	ELW135	-	-	0.5			$I_F = 16\text{mA}, I_O = 0.8\text{mA}, V_{CC}=4.5\text{V}$
	ELW 136 ELW4502 ELW4503	-	-	0.5			

Switching Characteristics ($T_A=0$ to 70°C unless specified otherwise, $I_F=16\text{mA}$, $V_{CC}=5\text{V}$)

Parameter	Symbol	Min	Typ.	Max.	Unit	Condition
Propagation Delay Time to Logic Low (Fig.8)	ELW135	-	0.36	1.5	μs	$R_L=4.1\text{K}\Omega$, $T_A=25^\circ\text{C}$
		-	-	2.0		$R_L=4.1\text{K}\Omega$
	ELW136 ELW4503	-	0.32	0.8		$R_L=1.9\text{K}\Omega$, $T_A=25^\circ\text{C}$
		-	-	1.0		$R_L=1.9\text{K}\Omega$
Propagation Delay Time to Logic High (Fig.8)	ELW135	-	0.45	1.5	μs	$R_L=4.1\text{K}\Omega$, $T_A=25^\circ\text{C}$
		-	-	2.0		$R_L=4.1\text{K}\Omega$
	ELW136 ELW4503	-	0.25	0.8		$R_L=1.9\text{K}\Omega$, $T_A=25^\circ\text{C}$
		-	-	1.0		$R_L=1.9\text{K}\Omega$
Common Mode Transient Immunity at Logic High (Fig.9) ^{*3}	ELW135	1,000	-	-	V/ μs	$I_F = 0\text{mA}$, $V_{CM}=10\text{Vp-p}$, $R_L=4.1\text{K}\Omega$, $T_A =25^\circ\text{C}$
	ELW136	1,000	-	-		$I_F = 0\text{mA}$, $V_{CM}=10\text{Vp-p}$, $R_L=1.9\text{K}\Omega$, $T_A =25^\circ\text{C}$
	ELW4503	15,000	20,000			$I_F = 0\text{mA}$, $V_{CM}=1500\text{Vp-p}$, $R_L=1.9\text{K}\Omega$, $T_A =25^\circ\text{C}$
Common Mode Transient Immunity at Logic Low (Fig.9) ^{*3}	ELW135	1,000	-	-	V/ μs	$I_F = 0\text{mA}$, $V_{CM}=10\text{Vp-p}$, $R_L=4.1\text{K}\Omega$, $T_A =25^\circ\text{C}$
	ELW136	1,000	-	-		$I_F = 0\text{mA}$, $V_{CM}=10\text{Vp-p}$, $R_L=1.9\text{K}\Omega$, $T_A =25^\circ\text{C}$
	ELW4503	15,000	20,000			$I_F = 0\text{mA}$, $V_{CM}=1500\text{Vp-p}$, $R_L=1.9\text{K}\Omega$, $T_A =25^\circ\text{C}$

* Typical values at $T_a = 25^\circ\text{C}$

Typical Electro-Optical Characteristics Curves

Figure 1. Forward Current vs Forward Voltage

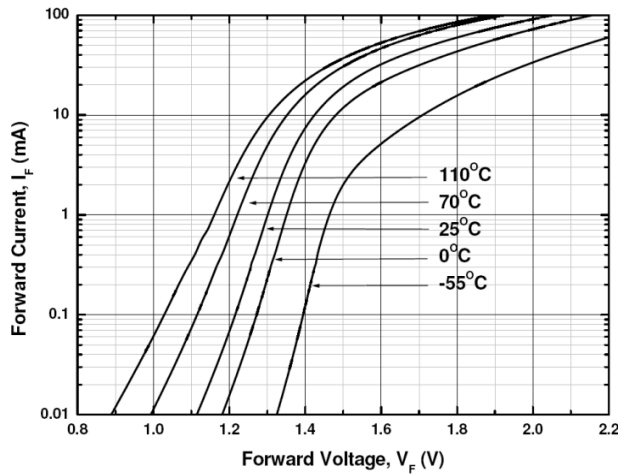


Figure 2. Current Transfer Ratio vs Forward Current

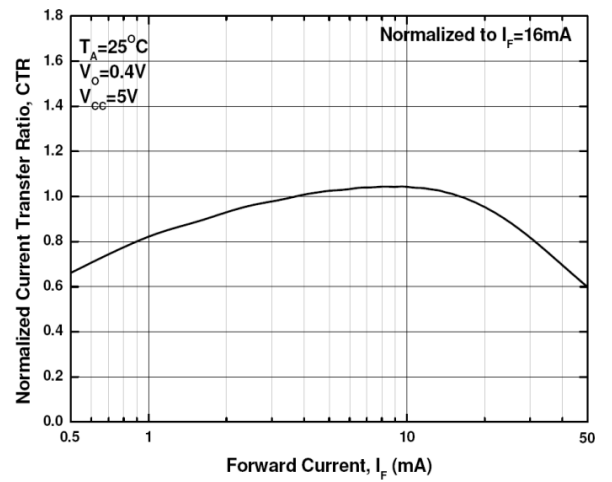


Figure 3. Current Transfer Ratio vs Ambient Temperature

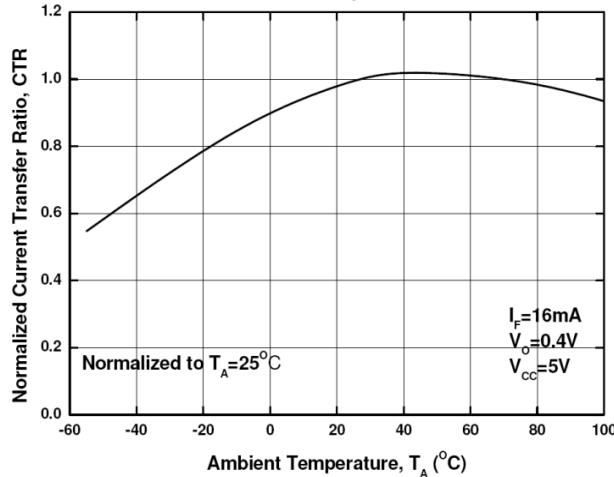


Figure 4. Output Current vs Output Voltage

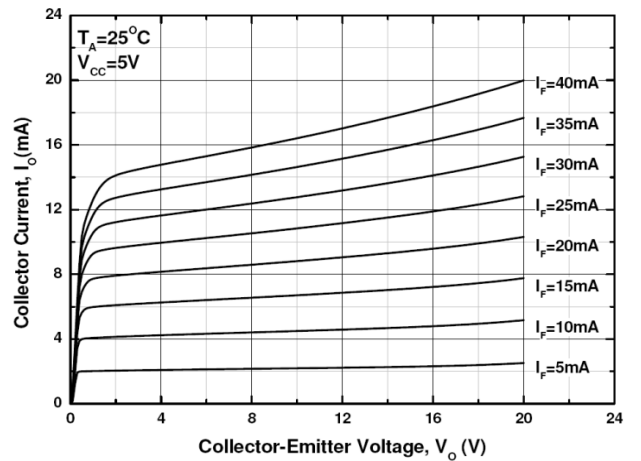


Figure 5. Logic High Output Current vs Ambient Temperature

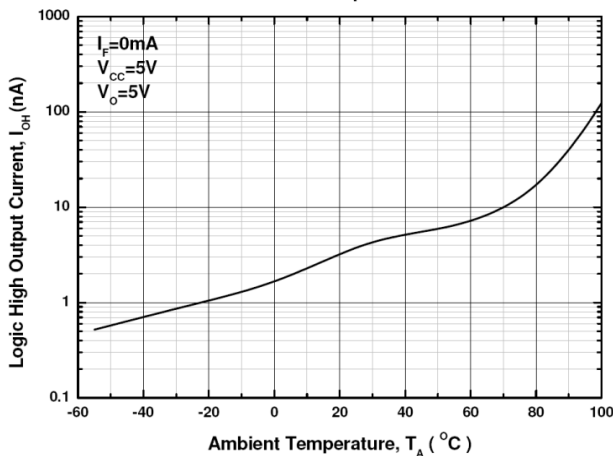


Figure 6. Propagation Delay vs. Load Resistance

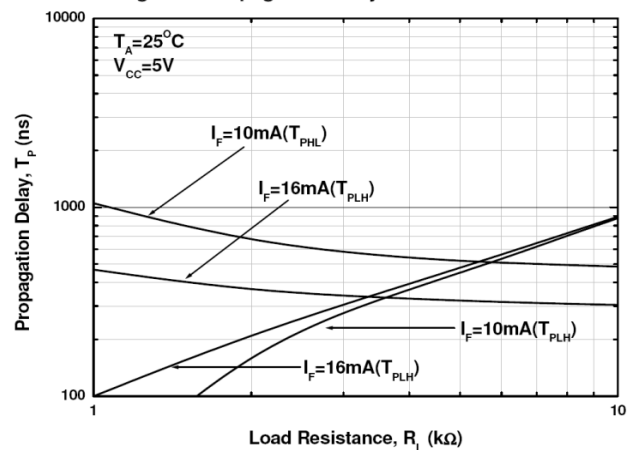


Figure 7. Propagation Delay vs. Temperature

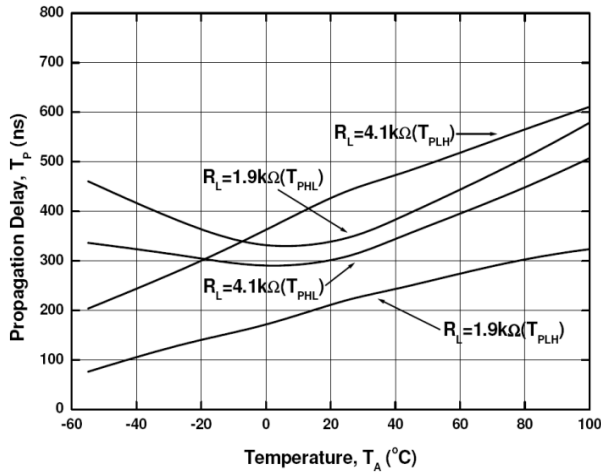


Figure 8 Switching Time Test Circuit & Waveform

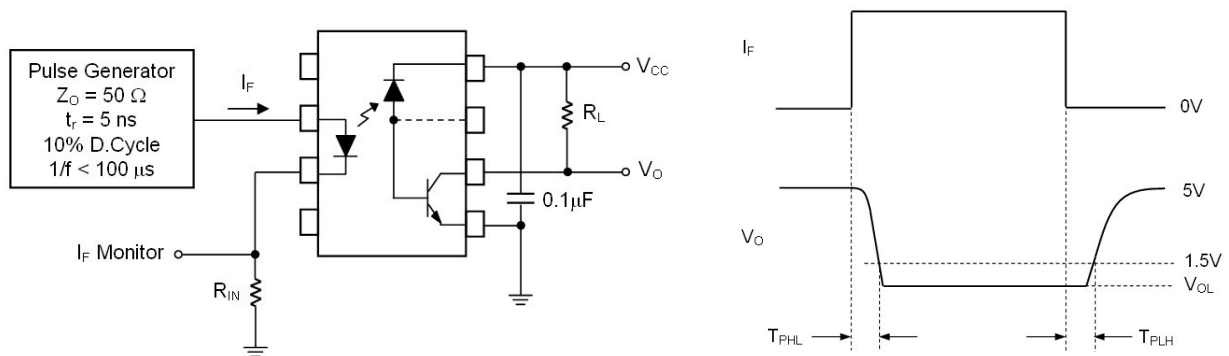
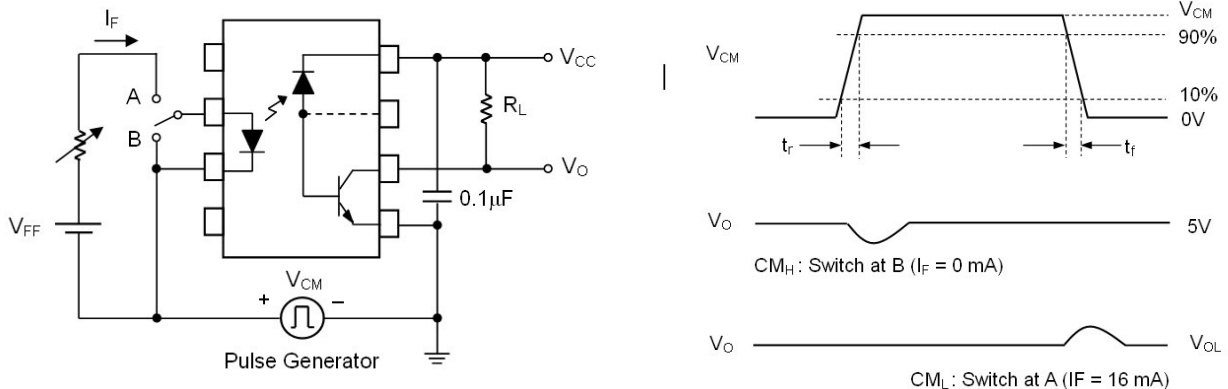


Figure 9 Transient Immunity Test Circuit & Waveform



Note:

*3 Common mode transient immunity in logic high level is the maximum tolerable (positive) dV_{cm}/dt on the leading edge of the common mode pulse signal V_{CM} , to assure that the output will remain in a logic high state (i.e., $V_O > 2.0V$).

Common mode transient immunity in logic low level is the maximum tolerable (negative) dV_{cm}/dt on the trailing edge of the common mode pulse signal, V_{CM} , to assure that the output will remain in a logic low state (i.e., $V_O < 0.8V$).

Order Information

Part Number

ELW13XY(Z)-V

or

ELW4503Y(Z)-V

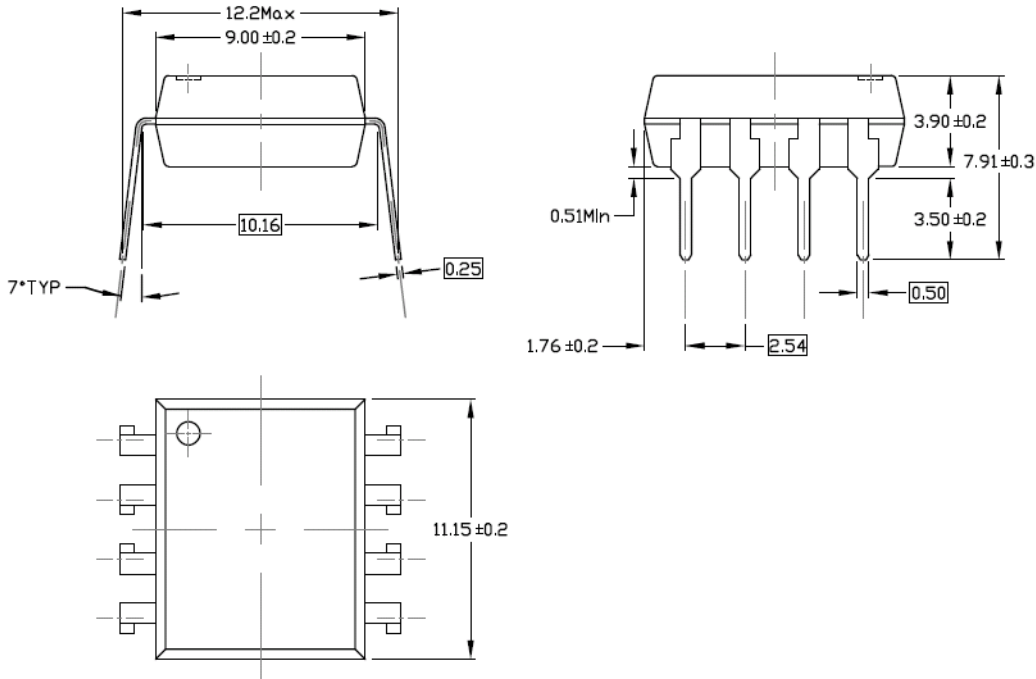
Note

- X = Part No. (X = 5 or 6)
- Y = Lead form option (S or none)
- Z = Tape and reel option (TA, TB or none)
- V = VDE (optional)

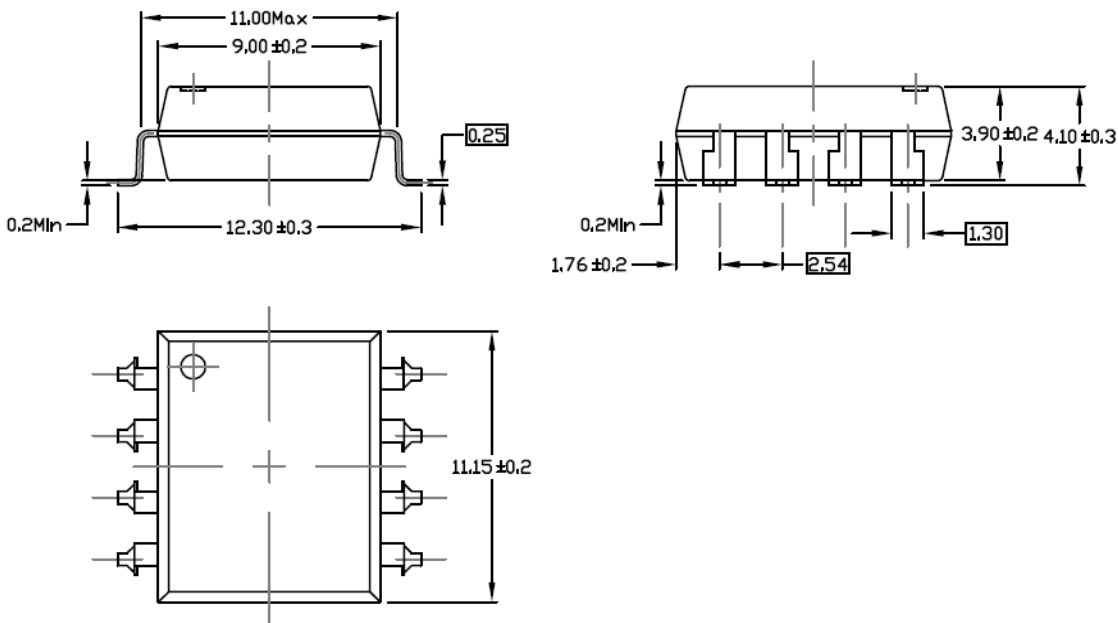
Option	Description	Packing quantity
None	Standard DIP-8	45 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel

Package Dimension
(Dimensions in mm)

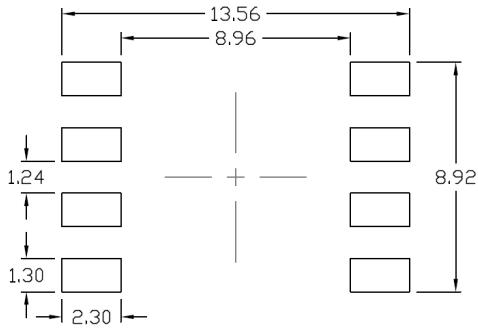
Standard DIP Type



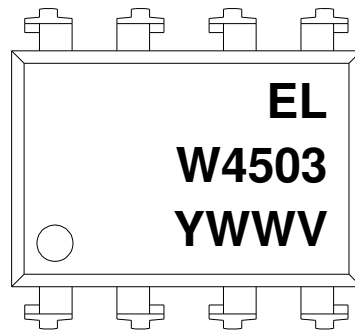
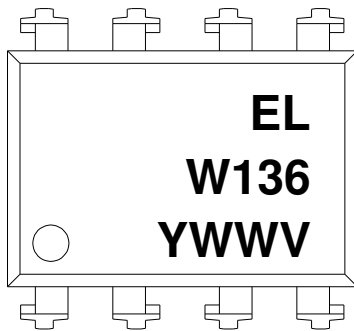
Option S Type



Recommended pad layout for surface mount leadform



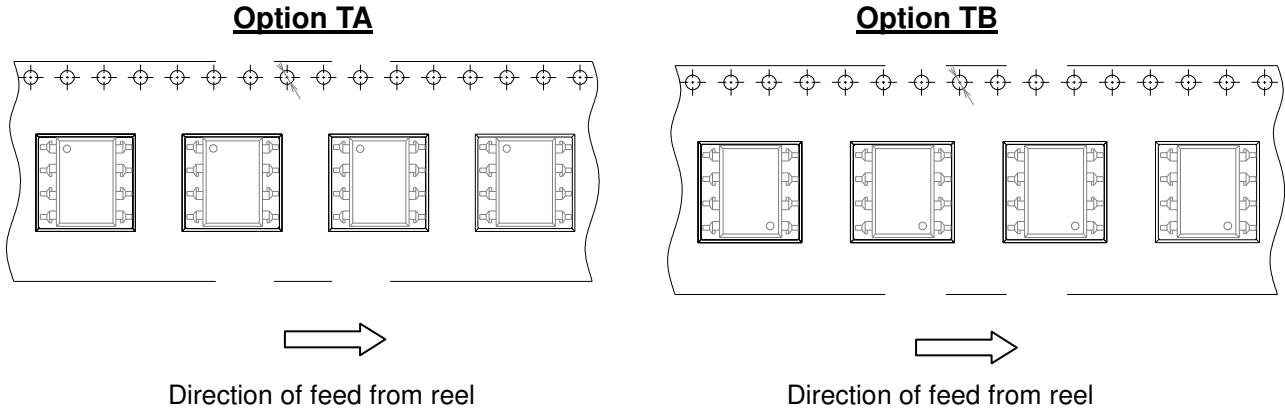
Device Marking



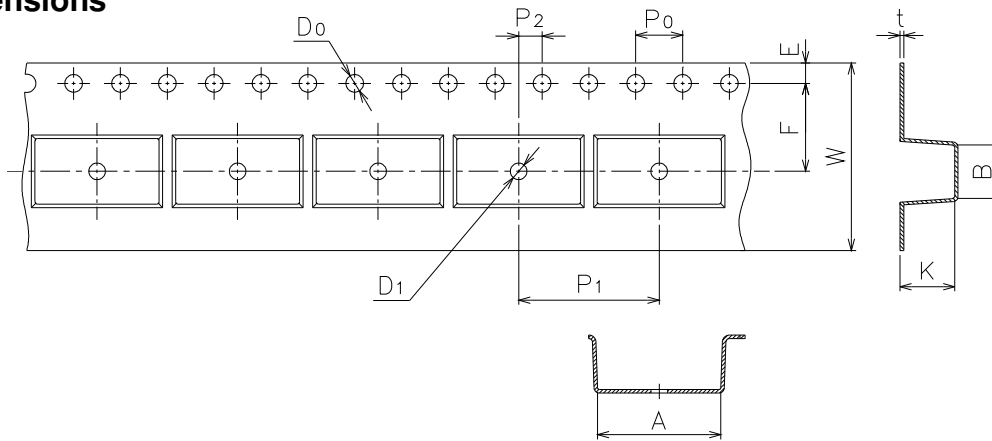
Notes

- EL denotes EVERLIGHT
- W4503 denotes Device Number
- W136 denotes Device Number
- Y denotes 1 digit Year code
- WW denotes 2 digit Week code
- V denotes VDE (optional)

Tape & Reel Packing Specifications



Tape dimensions

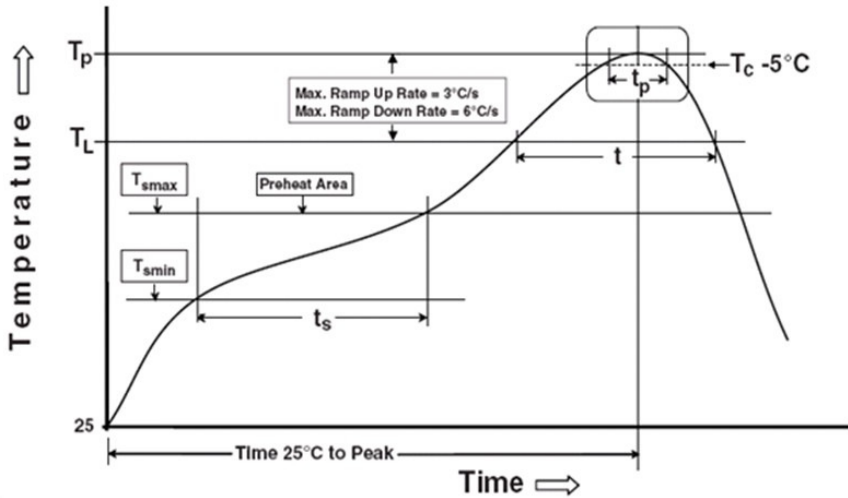


Dimension No.	A	B	Do	D1	E	F
Dimension(mm)	12.7±0.1	11.45±0.1	1.5±0.1	1.5±0.1	1.75±0.1	11.5±0.1
Dimension No.	Po	P1	P2	t	W	K
Dimension(mm)	4.0±0.1	16.0±0.1	2.0±0.1	0.4±0.05	24.00±0.3	4.6±0.1

Precautions for Use

1. Soldering Condition

1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile



Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin})	150 °C
Temperature max (T_{smax})	200 °C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max

Other

Liquidus Temperature (T_L)	217 °C
Time above Liquidus Temperature (t_L)	60-100 sec
Peak Temperature (T_p)	260 °C
Time within 5 °C of Actual Peak Temperature: $T_p - 5^\circ\text{C}$	30 s
Ramp- Down Rate from Peak Temperature	6 °C /second max.
Time 25 °C to peak temperature	8 minutes max.
Reflow times	3 times

DISCLAIMER

1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
3. These specification sheets include materials protected under copyright of EVERLIGHT corporation. Please don't reproduce or cause anyone to reproduce them without EVERLIGHT's consent.